

Samtec

QSTRIP®

(0.635 mm) .025"

MIS SERIES

MIXED TECHNOLOGY SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MIS

Insulator Material:

Liquid Crystal Polymer

Contact Material:

Phosphor Bronze

Plating:

Au or Sn over

50 μ " (1.27 μ m) Ni

Operating Temp Range:

-55 °C to +125 °C

Voltage Rating:

275 VAC

Max Cycles:

100

RoHS Compliant:

Yes

Board Mates:
MIT

Standoffs:
SO

PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (019-057)

Board Stacking:

For applications requiring more than two connectors per board contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

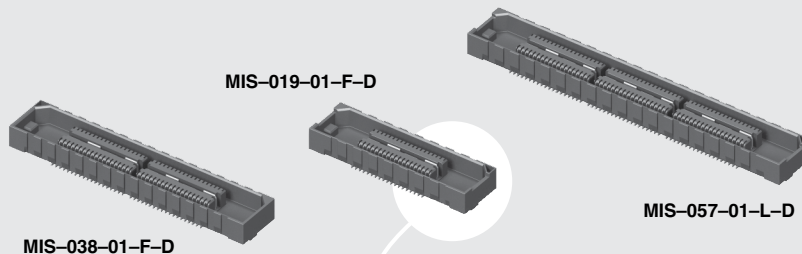


ALSO AVAILABLE (MOQ Required)

- 11 mm, 16 mm, 18.75 mm and 22 mm stack height
- 30 μ " (0.76 μ m) Gold
- Differential Pair and "Partitionable" (combine differential & single-ended banks in same connector) available.
- 76, 95, 114 and 133 positions per row

Note:

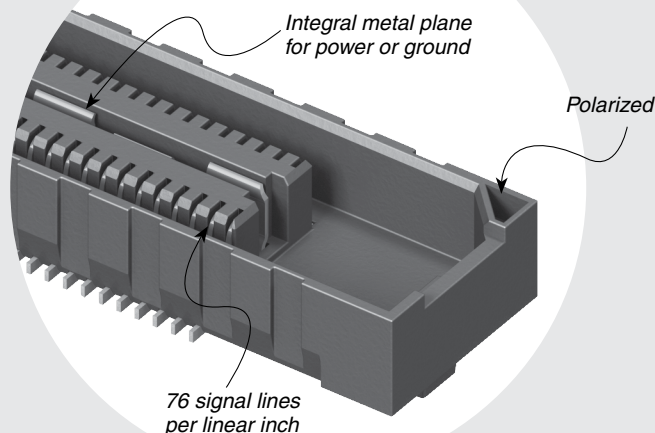
Some lengths, styles and options are non-standard, non-returnable.



MIS-019-01-F-D

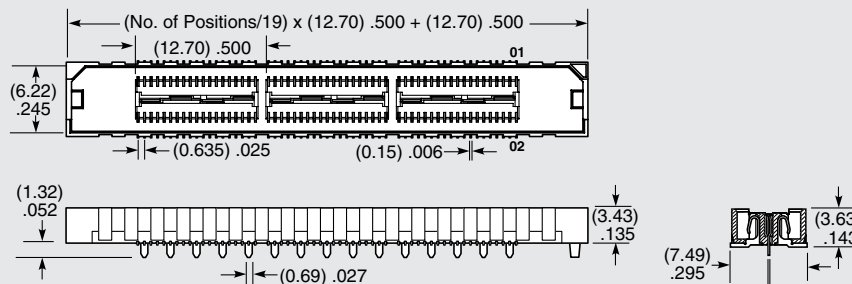
MIS-038-01-F-D

MIS-057-01-L-D



MIS	POSITIONS PER ROW	01	PLATING OPTION	D	OPTION	PACKAGING
	-019, -038, -057 (38 total positions per bank)		-F = Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails -L = 10 μ " (0.25 μ m) Gold on Signal Pins and Ground Plane, Matte Tin on tails -C* = Electro-Polished Selective 50 μ " (1.27 μ m) min Au over 150 μ " (3.81 μ m) Ni on Signal Pins in contact area, 10 μ " (0.25 μ m) min Au over 50 μ " (1.27 μ m) Ni on Ground Plane in contact area, Matte Tin over 50 μ " (1.27 μ m) min Ni on all solder tails		-K = (7.00 mm) .275" DIA Polyimide film Pick & Place Pad	Leave blank for tray packaging -TR = Tape & Reel -FR = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)

*Note:
-C Plating passes 10 year MFG testing



Note: Rugged through-hole ground plane soldered to board (requires paste-over-hole, not press-fit) for added retention to PCB.

MIS LEAD STYLE	MATED HEIGHT*	
	MIT LEAD STYLE -01	-02
-01	(5.00) .197	(8.00) .315

*Processing conditions will affect mated height. See SO Series for board space tolerances.

WWW.SAMTEC.COM

Unless otherwise approved in writing by Samtec, all parts and components are designed and built according to Samtec's specifications which are subject to change without notice.